

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Forward Voltage (Note 5)	@ $I_F = 10mA$	$V_{F}$	0.9	V

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6) $T_A = +25^{\circ}C$	$P_{D}$	250	mW
Thermal Resistance, Junction to Ambient Air	(Note 6) $T_A = +25^{\circ}C$	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Type Number	Marking Code	Zener Voltage Range (Note 5)			Maximum Zener Impedance f = 1kHz		Maximum Reverse Current (Note 5)		Temperature Coefficient @ I <sub>ZTC</sub> mV/°C		Test Current I <sub>ZTC</sub>		
		N1 00	Vz @ Izt		Izt	Z <sub>ZT</sub> @ I <sub>ZT</sub>		Izĸ	I <sub>R</sub>	@ V <sub>R</sub>			
D7T50C0\/4LD	WX	Nom (V)	Min (V)	Max (V)	mA	100		mA	μA	V	Min	Max	mA
BZT52C2V4LP BZT52C2V7LP	W1	2.4	2.20	2.60	5 5	100	600 600	1.0	50 20	1.0	-3.5 -3.5	0	5 5
			2.5	2.9	_	100			_	1.0			
BZT52C3V0LP	W2	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0	5
BZT52C3V3LP	W3	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0	5
BZT52C3V6LP	W4	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0	5
BZT52C3V9LP	W5	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V3LP	W6	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V7LP	W7	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2	5
BZT52C5V1LP	9Y	5.1	4.8	5.4	5	60	480	1.0	2.0	2.0	-2.7	1.2	5
BZT52C5V6LP	9A	5.6	5.2	6.0	5	40	400	1.0	1.0	2.0	-2	2.5	5
BZT52C6V2LP	9B	6.2	5.8	6.6	5	10	150	1.0	3.0	4.0	0.4	3.7	5
BZT52C6V8LP (Note 7)	9C	6.8	6.4	7.2	5	15	80	1.0	2.0	4.0	1.2	4.5	5
BZT52C7V5LP	9D	7.5	7.0	7.9	5	15	80	1.0	1.0	5.0	2.5	5.3	5
BZT52C8V2LP	9E	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2	5
BZT52C9V1LP	9F	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZT52C10LP	9G	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0	5
BZT52C11LP	9H	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0	5
BZT52C12LP	9J	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0	5
BZT52C13LP	9K	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZT52C15LP	9L	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0	5
BZT52C16LP	9M	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0	5
BZT52C18LP	9N	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0	5
BZT52C20LP	9P	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	-	5
BZT52C22LP	9R	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	-	5
BZT52C24LP	9S	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	-	5
BZT52C36LP	9W	36	34.0	38.0	2	90	350	0.5	0.1	25.2	36.5	-	5
BZT52C39LP	9X	39	37.0	41.0	2	130	350	0.5	0.1	27.3	36.8	-	5

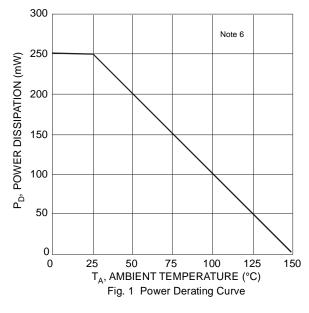
Notes:

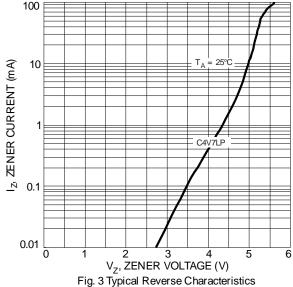
<sup>5.</sup> Short duration pulse test used to minimize self-heating effect.6. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com.

7. Device can withstand a repetitive, 1A pulse with tp = 300µs and T = 3s (forward or reverse direction).









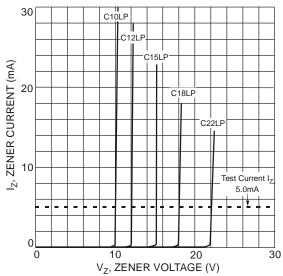
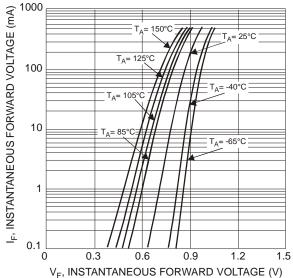


Fig. 5 Typical Zener Breakdown Characteristics



 $V_{\rm F}$ , INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics

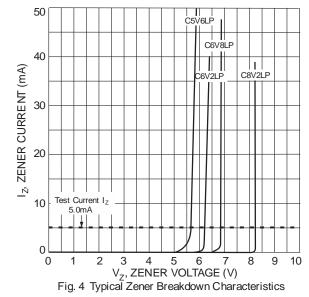
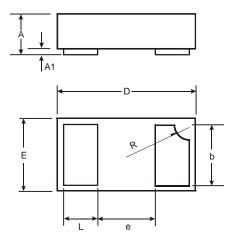


Fig. 6 Typical Zener Breakdown Characteristics



## **Package Outline Dimensions**

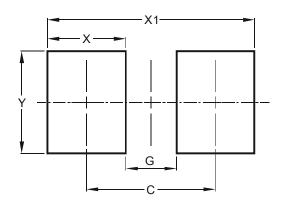
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-2					
Dim	Min	Тур			
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.40		
Ĺ	0.20	0.30	0.25		
R	0.05	0.15	0.10		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Y	0.70



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